



1/10

FIG. 1 A

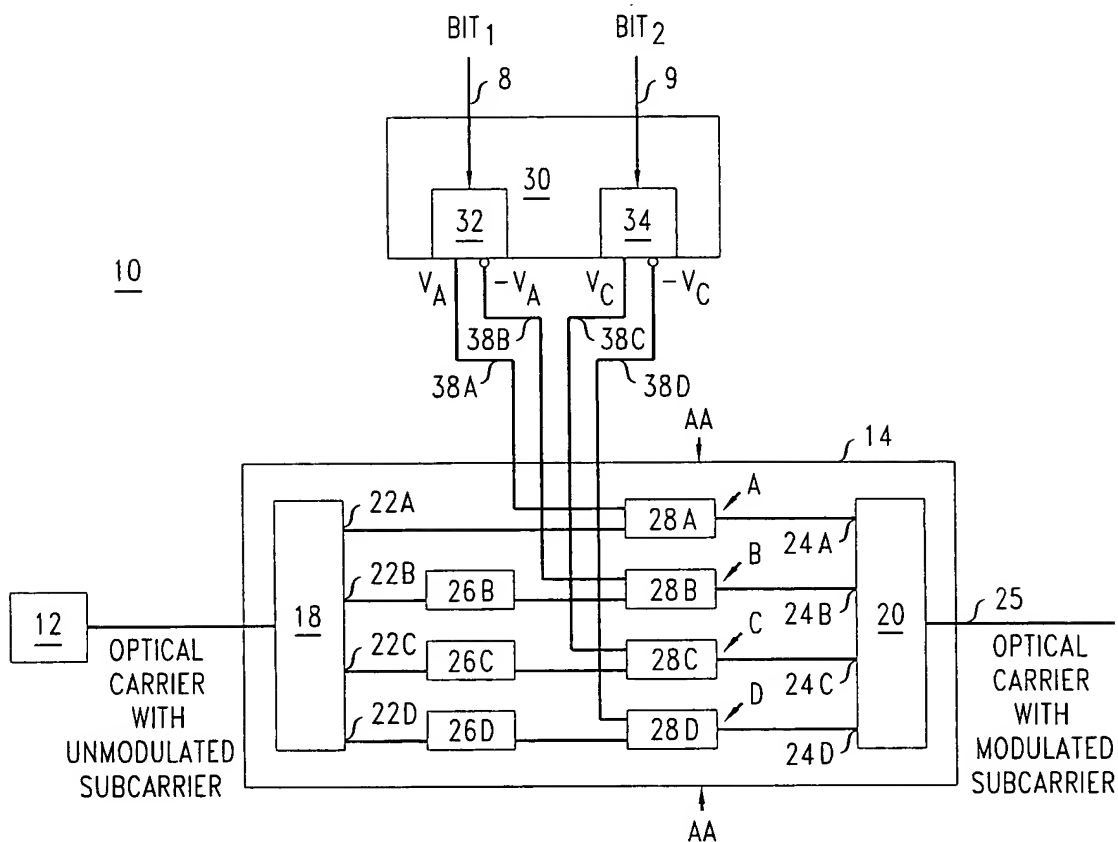
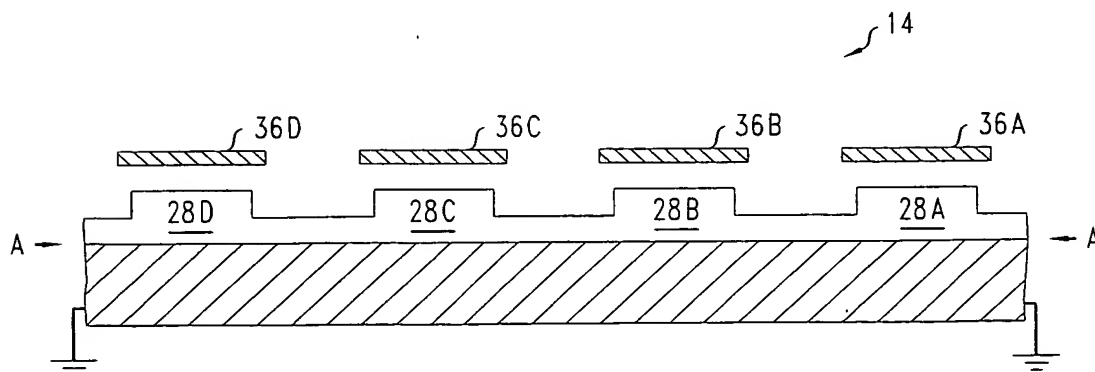


FIG. 1 B



2/10

FIG. 2

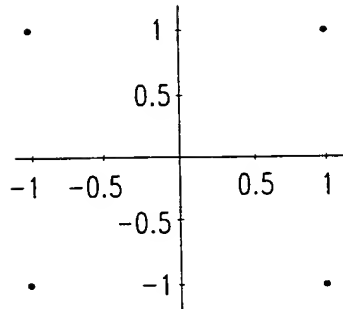


FIG. 3

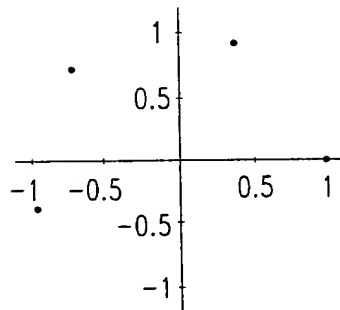
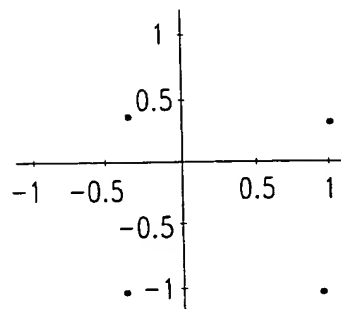
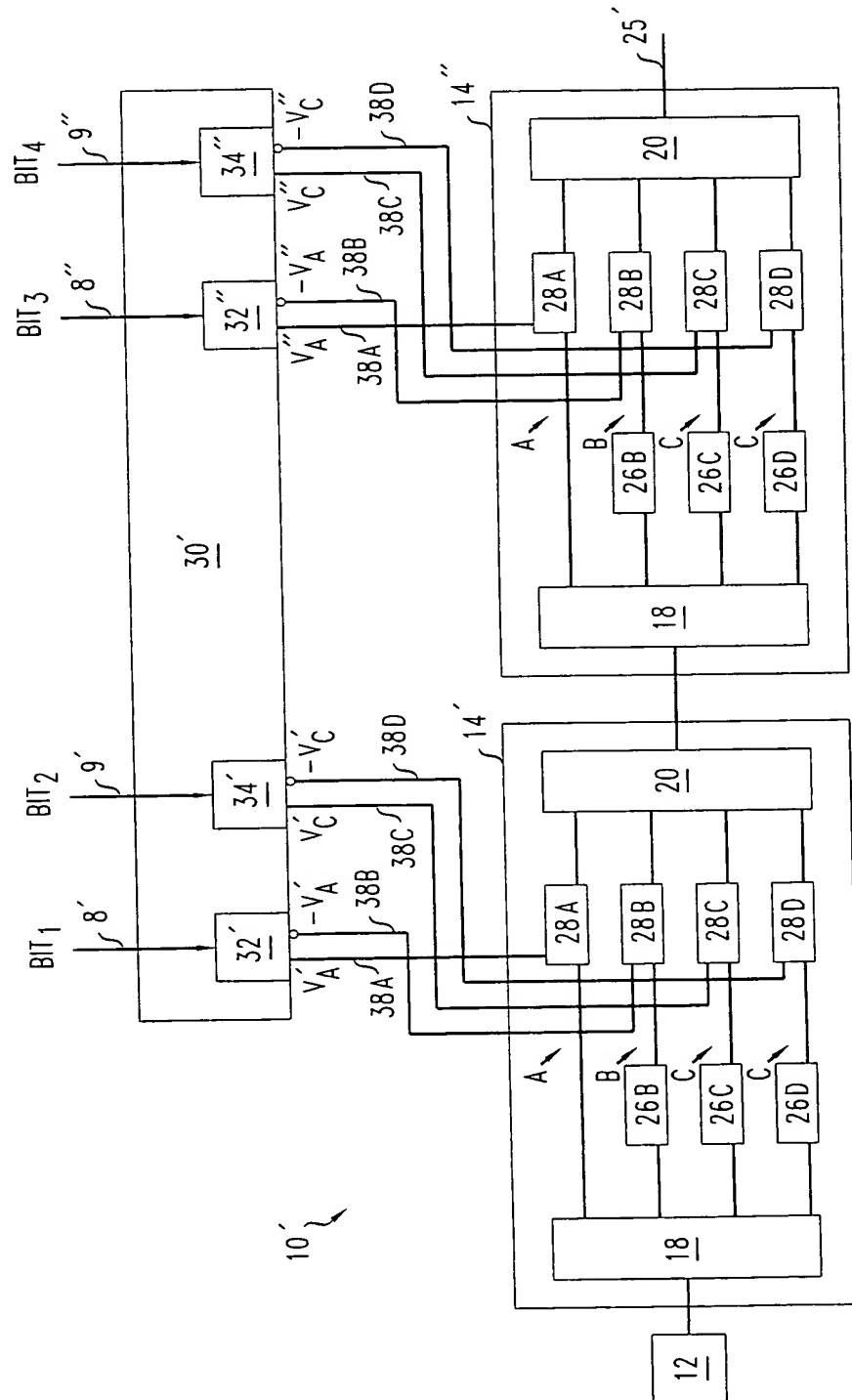


FIG. 4



3/10

FIG. 5



4/10

FIG. 6 A

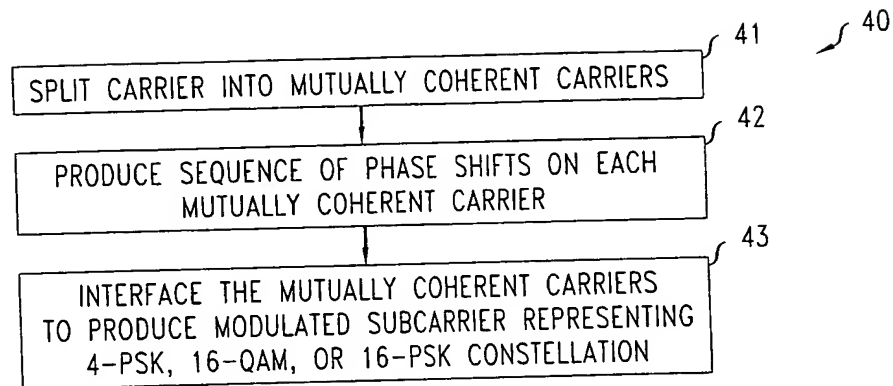
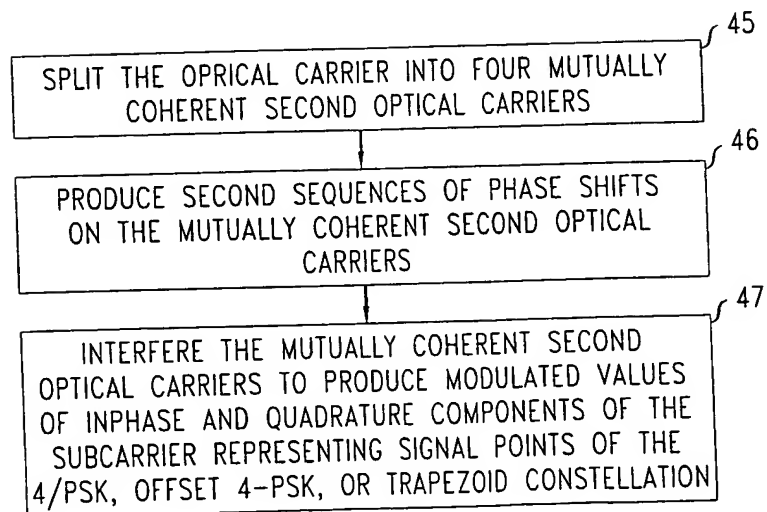


FIG. 6 B



5/10

FIG. 7A

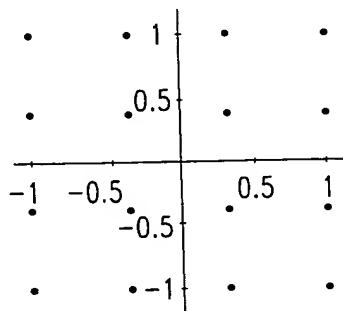
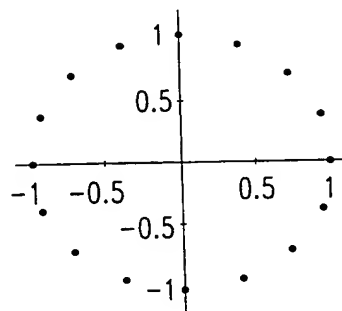


FIG. 7B



A cross-sectional view of a multi-layered structure 71. The structure consists of four horizontal layers. The top layer is labeled 56. The second layer from the top is labeled 54. The third layer from the top is labeled 52. The bottom layer is unlabeled. A hatched rectangular region is located on the top surface of the top layer 56, labeled 58. An arrow points to the left from the label 71, indicating the structure's extent.

73 ←

58 60 62 52

Diagram 74 is a cross-sectional view of a device structure. It shows a substrate 52 with a thin layer 54 on its top surface. A thick layer 56 is deposited on top of layer 54. On the right side of layer 56, there is a rectangular block 60. On top of block 60 is a smaller, hatched rectangular block 58. The label "BCB" is located in the upper left corner of the diagram.

7/10

FIG. 12

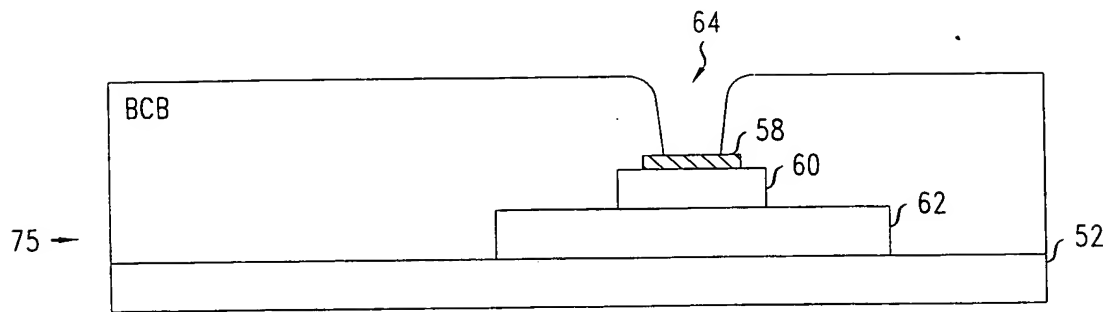


FIG. 13

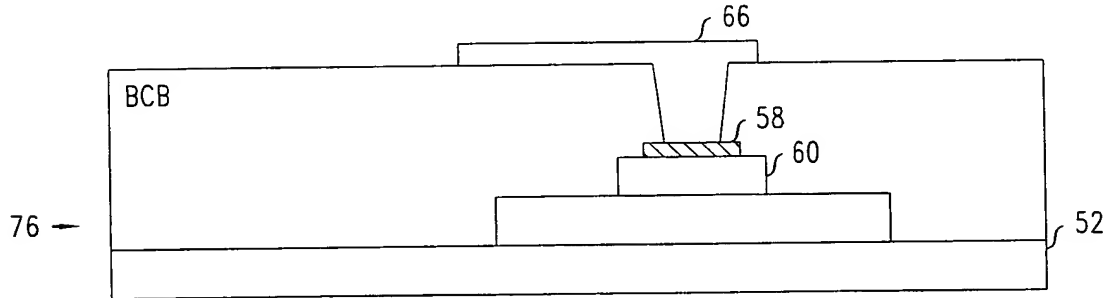
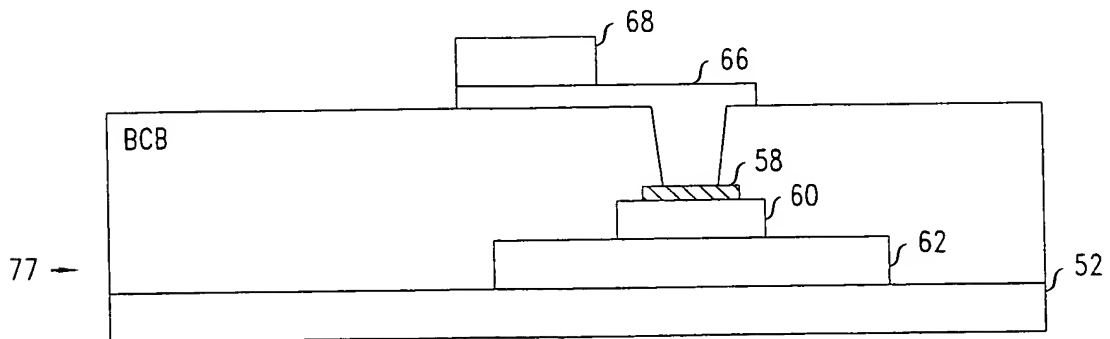
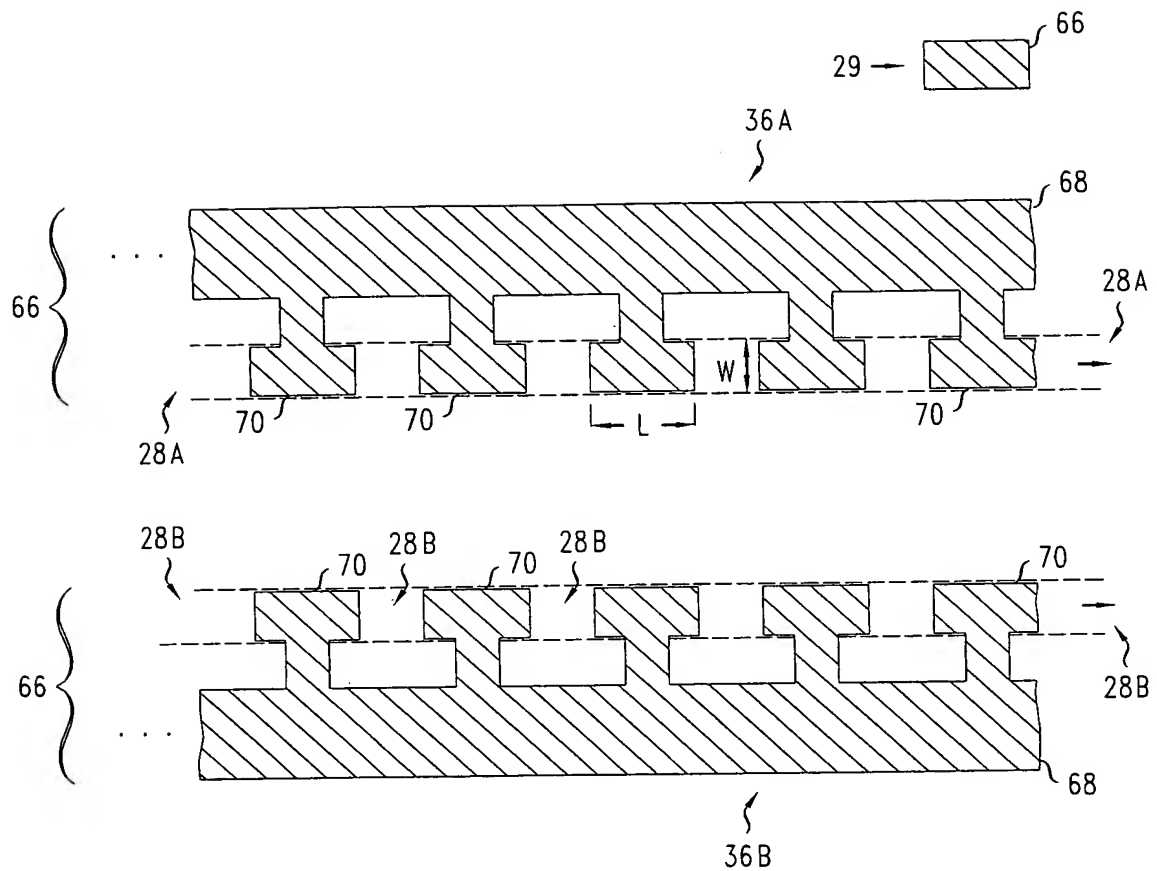


FIG. 14



8/10

FIG. 15





9/10

FIG. 16 A

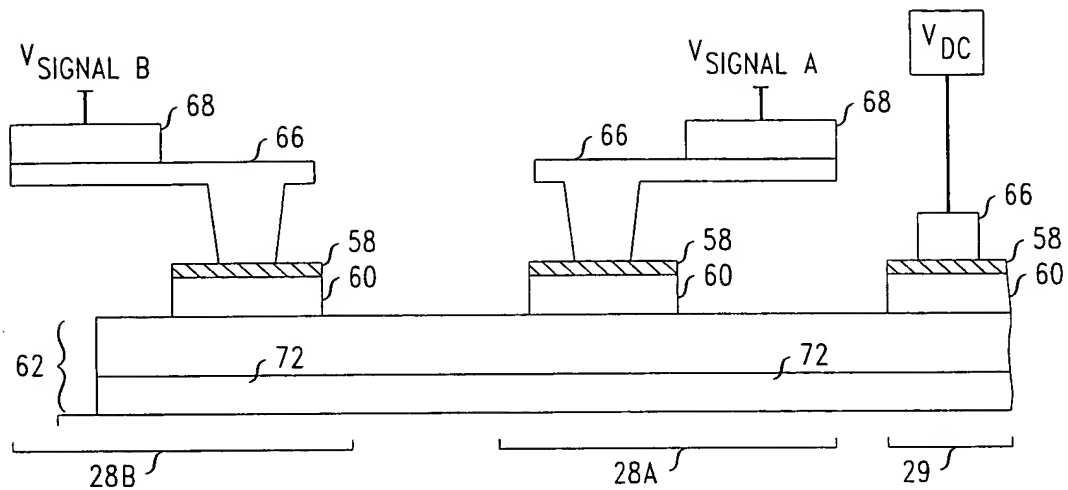
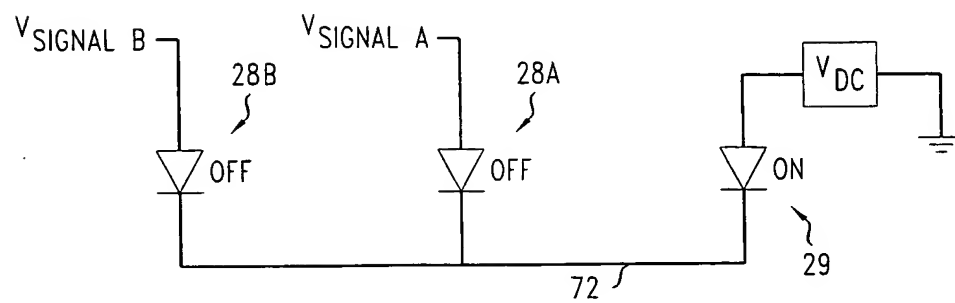


FIG. 16 B



10/10

FIG. 17

